CLAIMS

What is claimed is:

1. A method comprising:

aligning first and second sets of terminals of an integrated circuit (IC) with corresponding third and fourth sets of terminals of a substrate, the first and second sets of terminals being in first and second zones, respectively, of the IC;

coupling the first and third sets of terminals with a first type of connector; and

coupling the second and fourth sets of terminals with a second type of connector.

2. The method recited in claim 1, including forming the first and second sets of terminals on a surface of the IC.

3. The method recited in claim 2, including forming the first zone in a central region of the surface.

4. The method recited in claim 2, including forming the second zone in a peripheral region of the surface.

5. The method recited in claim 1, wherein coupling the first and third sets of terminals with the first type of connector comprises using solder.

6. The method recited in claim 1, wherein coupling the second and fourth sets of terminals with the second type of connector comprises using a solderless, compliant, electrically conductive material.

7. The method recited in claim 1, wherein coupling the second and fourth sets of terminals with the second type of connector comprises using a connector from the group comprising a nanospring, a sea of leads connector, and an interposer.

8. The method recited in claim 1, wherein coupling the second and fourth sets of terminals with the second type of connector comprises physically compressing the IC and the substrate together.

9. A method comprising:

aligning first and second sets of terminals of an integrated circuit (IC) package with corresponding third and fourth sets of terminals of a substrate, the first and second sets of terminals being in first and second zones, respectively, of the IC package;

coupling the first and third sets of terminals with a first type of connector; and

coupling the second and fourth sets of terminals with a second type of connector.

10. The method recited in claim 9, including forming the first and second sets of terminals on a surface of the IC package.

11. The method recited in claim 10, including forming the first zone in a central region of the surface.

12. The method recited in claim 10, including forming the second zone in a peripheral region of the surface.

13. The method recited in claim 9, wherein coupling the first and third sets of terminals with the first type of connector comprises using solder.

14. The method recited in claim 9, wherein coupling the second and fourth sets of terminals with the second type of connector comprises using a solderless, compliant, electrically conductive material.

15. The method recited in claim 9, wherein coupling the second and fourth sets of terminals with the second type of connector comprises using a connector from the group comprising a nanospring, a sea of leads connector, and an interposer.

16. The method recited in claim 9, wherein coupling the second and fourth sets of terminals with the second type of connector comprises physically compressing the IC package and the substrate together.

17. An electronic package comprising:

a die comprising first and second sets of terminals disposed in first and second zones, respectively, of the die;

a substrate comprising third and fourth sets of terminals;

a first type of connector to couple the first and third sets of terminals; and

a second type of connector to couple the second and fourth sets of terminals.

18. The electronic package recited in claim 17, wherein the first and second sets of terminals are disposed on a surface of the die.

19. The electronic package recited in claim 17, wherein the first zone is centrally located on the surface.

20. The electronic package recited in claim 17, wherein the second zone is peripherally located on the surface.

21. The electronic package recited in claim 17, wherein the first type of connector comprises solder.

22. The electronic package recited in claim 17, wherein the second type of connector comprises a compliant, electrically conductive material.

23. The electronic package recited in claim 17, wherein the second type of connector is from the group comprising a nanospring, a sea of leads connector, and an interposer.

24. The electronic package recited in claim 17, wherein the second type of connector comprises an interposer, and wherein the electronic package further comprises:

an element to physically compress the die and the substrate together to electrically couple the die to the substrate.

25. The electronic package recited in claim 24, wherein the interposer comprises:

a flexible support formed of electrically insulating material; and

a plurality of elements formed of electrically conductive material.

26. The electronic package recited in claim 17, wherein the second type of connector comprises a compressible element to electrically couple the die to the substrate.

27. The electronic package recited in claim 17, wherein the die further comprises a fifth set of terminals disposed in a third zone of the die, wherein the substrate comprises a sixth set of terminals, and wherein the electronic package further comprises:

a third type of connector to couple the fifth and sixth sets of terminals.

28. The electronic package recited in claim 27, wherein the first, second, and fifth sets of terminals are disposed on a surface of the die, wherein the first zone is centrally located on the surface, wherein the second zone is peripherally located on the surface, and wherein the third zone is located on the surface between the first and second zones.

29. The electronic package recited in claim 27, wherein the first type of connector comprises solder, and wherein the second and third types of connectors comprise compliant material.

30. The electronic package recited in claim 27, wherein the first type of connector comprises solder, and wherein the second and third types of connectors are from the group comprising a nanospring, a sea of leads connector, and an interposer.

31. An electronic assembly comprising:

an integrated circuit (IC) package comprising first and second sets of terminals disposed in first and second zones, respectively, of a surface of the IC package;

a substrate comprising third and fourth sets of terminals;

a first type of connector to couple the first and third sets of terminals; and

a second type of connector to couple the second and fourth sets of terminals.

32. The electronic assembly recited in claim 31, wherein the first zone is centrally located on the surface, and wherein the first type of connector comprises solder.

33. The electronic assembly recited in claim 31, wherein the second zone is peripherally located on the surface, and wherein the second type of connector comprises a compliant, electrically conductive material.

34. The electronic assembly recited in claim 31, wherein the second type of connector is from the group comprising a nanospring, a sea of leads connector, and an interposer.

35. The electronic assembly recited in claim 31, wherein the second type of connector comprises an interposer, and wherein the electronic assembly further comprises:

an element to physically compress the IC package and the substrate together to electrically couple the IC package to the substrate.

36. An electronic system having at least one electronic assembly comprising:

a die comprising first and second sets of terminals disposed in first and second zones, respectively, of a surface of the die;

a substrate comprising third and fourth sets of terminals;

a first type of connector to couple the first and third sets of terminals; and

a second type of connector to couple the second and fourth sets of terminals.

37. The electronic system recited in claim 36, wherein the first zone is centrally located on the surface, and wherein the first type of connector comprises solder.

38. The electronic system recited in claim 36, wherein the second zone is peripherally located on the surface, and wherein the second type of connector comprises a compliant, electrically conductive material.

39. A data processing system comprising:

a bus coupling components in the data processing system; and

a processor coupled to the bus and including at least one electronic package comprising:

a die comprising first and second sets of terminals disposed in first and second zones, respectively, of a surface of the die;

a substrate comprising third and fourth sets of terminals;

a first type of connector to couple the first and third sets of terminals; and

a second type of connector to couple the second and fourth sets of terminals.

40. The data processing system recited in claim 39, wherein the first zone is centrally located on the surface, and wherein the first type of connector comprises solder.

41. The data processing system recited in claim 39, wherein the second zone is peripherally located on the surface, and wherein the second type of connector comprises a compliant, electrically conductive material.

42. The data processing system recited in claim 39 and further comprising:

a display coupled to the bus; and

external memory coupled to the bus.